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	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	B RS	1	5371950.pn.	USPAT; EPO; JPO	2003/06 /12			0
2	B RS	54	kathryn and omalley	USPAT; EPO; JPO	2003/06 /26			0
3	B RS	0	maeda-norio.in	USPAT; EPO; JPO	2003/06 /26			0
4	B RS	58	maeda-norio.in.	USPAT; EPO; JPO	2003/06 /26			0
5	B RS	142	sumi-koji.in.	USPAT; EPO; JPO	2003/06 /26			0
6	B RS	36	aihara-hiroshi.in.	USPAT; EPO; JPO	2003/06 /26			0
7	B RS	3	oono-masao.in.	USPAT; EPO; JPO	2003/06 /26			0
8	B RS	458	matsumoto-takao.in.	USPAT; EPO; JPO	2003/06 /26			0
9	B RS	7	izutani-naoaki.in.	USPAT; EPO; JPO	2003/06 /26			0
10	B RS	693	maeda-norio.in. sumi-koji.in. aihara-hiroshi.in. oono-masao.in. matsumoto-takao.in. izutani-naoaki.in.	USPAT; EPO; JPO	2003/06 /26 14:47			0
11	B RS	0	(maeda-norio.in. sumi-koji.in. aihara-hiroshi.in. oono-masao.in. matsumoto-takao.in. izutani-naoaki.in.) and (34/\$.ccls. 134/\$.ccls.)	USPAT; EPO; JPO	2003/06 /26 14:47			0
12	B RS	100	(maeda-norio.in. sumi-koji.in. aihara-hiroshi.in. oono-masao.in. matsumoto-takao.in. izutani-naoaki.in.) and (substrate wafer)	USPAT; EPO; JPO	2003/06 /26 14:48			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
13	B RS	3	(maeda-norio.in. sumi-koji.in. aihara-hiroshi.in. oono-masao.in. matsumoto-takao.in. izutani-naoaki.in.) and (dry with (substrate wafer))	USPAT; EPO; JPO	2003/06 /26 14:48			0
14	B RS	3	(maeda-norio.in. sumi-koji.in. aihara-hiroshi.in. oono-masao.in. matsumoto-takao.in. izutani-naoaki.in.) and ((dry clean) with (substrate wafer))	USPAT; EPO; JPO	2003/06 /26 14:52			0
15	B RS	1	5964958.bn.	USPAT; EPO; JPO	2003/06 /26			0
16	B RS	0	pj-09103686-\$ did.	USPAT; EPO; JPO	2003/06 /26			0
17	B RS	0	jpj-06103686-\$ did.	USPAT; EPO; JPO	2003/06 /26			0
18	B RS	0	jpj-6103686-\$ did.	USPAT; EPO; JPO	2003/06 /26			0
19	B RS	0	jp-6103686-\$ did.	USPAT; EPO; JPO	2003/06 /26			0
20	B RS	1	jp-06103686-\$ did.	USPAT; EPO; JPO	2003/06 /26			0
21	B RS	1	jp-11176796-\$ did.	USPAT; EPO; JPO	2003/06 /26			0
22	B RS	1	jp-11345798-\$ did.	USPAT; EPO; JPO	2003/06 /26			0
23	B RS	1	jp-10335299-\$ did.	USPAT; EPO; JPO	2003/06 /26			0
24	B RS	0	jp-200012505-\$ did.	USPAT; EPO; JPO	2003/06 /26			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
25	B RS	24	("4778532" "4828751" "5022961" "5143103" "5940985" "4577650" "4633893" "4738272" "4740249" "4778532" "4795497" "4813851" "4856544" "4899767" "4911761" "4917123" "4984597" "5383484" "5520744" "5556479" "5653045" "5660642" "5685086" "5846338" "5882433").pn.	USPAT; EPO; JPO	2003/06 /29 14:33			0
26	B RS	23	((("4778532" "4828751" "5022961" "5143103" "5940985" "4577650" "4633893" "4738272" "4740249" "4778532" "4795497" "4813851" "4856544" "4899767" "4911761" "4917123" "4984597" "5383484" "5520744" "5556479" "5653045" "5660642" "5685086" "5846338" "5882433").pn.) and (liquid drops)	USPAT; EPO; JPO	2003/06 /27 14:54			0
27	B RS	175 0	134/902.ccls.	USPAT; EPO; JPO	2003/06 /26			0
28	B RS	524	134/902.ccls. and (dry\$3 with (wafer substrate)) and (clean\$4 with (wafer substrate))	USPAT; EPO; JPO	2003/06 /26 17:23			0
29	B RS	164	(134/902.ccls. and (dry\$3 with (wafer substrate)) and (clean\$4 with (wafer substrate))) and drops	USPAT; EPO; JPO	2003/06 /26 17:23			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
30	B RS	62	(134/902.ccls. and (dry\$3 with (wafer substrate)) and (clean\$4 with (wafer substrate))) and (drops with (fluid liquid))	USPAT; EPO; JPO	2003/06 /26 17:24			0
31	B RS	61	((134/902.ccls. and (dry\$3 with (wafer substrate)) and (clean\$4 with (wafer substrate))) and (drops with (fluid liquid))) not (((4778532" "4828751" "5022961" "5143103" "5940985" "4577650" "4633893" "4738272" "4740249" "4778532" "4795497" "4813851" "4856544" "4899767" "4911761" "4917123" "4984597" "5383484" "5520744" "5556479" "5653045" "5660642" "5685086" "5846338" "5882433").pn.) and (liquid drops))	USPAT; EPO; JPO	2003/06 /29 14:17			0
32	B RS	1	6430840.pn.	USPAT; EPO; JPO	2003/06 /27			0
33	B RS	1	6430840.pn. and room	USPAT; EPO; JPO	2003/06 /27			0
34	B RS	0	kr-200044984-\$ did.	USPAT; EPO; JPO	2003/06 /27			0
35	B RS	0	kr-200044984-\$ did.	USPAT; EPO; JPO; DERWEN	2003/06 /27 14:22			0
36	B RS	10	("4911761" "5951779" "6029371" "6050275" "6123900").pn.	USPAT; EPO; JPO; DERWEN	2003/06 /29 14:04			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
37	B RS	14	(("4984597" "5191908" "5275184" "5443540" "5464480" "5520744" "5540245" "5569330" "5575079" "5660642" "5714203" "5752532" "5807439" "5878760").pn.) and (liquid drops)	USPAT; EPO; JPO	2003/06 /27 15:10			0
38	B RS	571 7	hamano.in.	USPAT; EPO; JPO	2003/06 /27			0
39	B RS	1	jp-09213672-\$ did.	USPAT; EPO; JPO	2003/06 /27			0
40	B RS	2	6123900.pn.	USPAT; EPO; JPO; DERWEN	2003/06 /29 15:18			0
41	B RS	61	((134/902.ccls. and (dry\$3 with (wafer substrate)) and (clean\$4 with (wafer substrate))) and (drops with (fluid liquid))) not (((("4778532" "4828751" "5022961" "5143103" "5940985" "4577650" "4633893" "4738272" "4740249" "4778532" "4795497" "4813851" "4856544" "4899767" "4911761" "4917123" "4984597" "5383484" "5520744" "5556479" "5653045" "5660642" "5685086" "5846338" "5882433").pn.) and (liquid drops))	USPAT; EPO; JPO	2003/06 /29 14:34			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
42	B RS	54	(((134/902.ccls. and (dry\$3 with (wafer substrate)) and (clean\$4 with (wafer substrate))) and (drops with (fluid liquid))) not (((4778532" "4828751" "5022961" "5143103" "5940985" "4577650" "4633893" "4738272" "4740249" "4778532" "4795497" "4813851" "4856544" "4899767" "4911761" "4917123" "4984597" "5383484" "5520744" "5556479" "5653045" "5660642" "5685086" "5846338" "5882433").pn.) and (liquid drops)) and (inert nitrogen)	USPAT; EPO; JPO	2003/06 /29 14:18			0
43	B RS	24	(((134/902.ccls. and (dry\$3 with (wafer substrate)) and (clean\$4 with (wafer substrate))) and (drops with (fluid liquid))) not (((4778532" "4828751" "5022961" "5143103" "5940985" "4577650" "4633893" "4738272" "4740249" "4778532" "4795497" "4813851" "4856544" "4899767" "4911761" "4917123" "4984597" "5383484" "5520744" "5556479" "5653045" "5660642" "5685086" "5846338" "5882433").pn.) and (liquid drops)) and (inert nitrogen)) and bath	USPAT; EPO; JPO	2003/06 /29 14:35			0

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
44	B RS	7 (((134/902.ccls. and (dry\$3 with (wafer substrate)) and (clean\$4 with (wafer substrate))) and (drops with (fluid liquid))) not (((4778532" "4828751" "5022961" "5143103" "5940985" "4577650" "4633893" "4738272" "4740249" "4778532" "4795497" "4813851" "4856544" "4899767" "4911761" "4917123" "4984597" "5383484" "5520744" "5556479" "5653045" "5660642" "5685086" "5846338" "5882433").pn.) and (liquid drops))) and kamikawa.in.	USPAT; EPO; JPO	2003/06 /29 14:34			0
45	B RS	32 kamikawa.in. and ipa and (nitrogen inert)	USPAT; EPO; JPO	2003/06 /29			0
46	B RS	38 134/902.ccls. and (circulate with (water diw (clean\$3 near2 fluid)))	USPAT; EPO; JPO; DERWEN	2003/06 /29 15:29			0
47	B RS	16 (134/902.ccls. and (circulate with (water diw (clean\$3 near2 fluid)))) and (isoprop\$4 ipa)	USPAT; EPO; JPO; DERWEN	2003/06 /29 15:20			0
48	B RS	2 134/902.ccls. and (circulate with (isoprop\$4 ipa (dry\$3 near2 fluid)))	USPAT; EPO; JPO; DERWEN	2003/06 /29 15:31			0
49	B RS	16 134/902.ccls. and (circulat\$3 with (isoprop\$4 ipa (dry\$3 near2 fluid)))	USPAT; EPO; JPO; DERWEN	2003/06 /29 21:15			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
50	B RS	0	134/902.ccls. and ((init\$4 near2 speed) with (ipa isoprop\$4 (dry\$3 near2 fluid)))	USPAT; EPO; JPO; DERWEN	2003/06 /29 21:16			0
51	B RS	18	134/902.ccls. and (speed with (ipa isoprop\$4 (dry\$3 near2 fluid)))	USPAT; EPO; JPO; DERWEN	2003/06 /29 21:38			0
52	B RS	14	134/902.ccls. and ((flow near2 rate) with (ipa isoprop\$4 (dry\$3 near2 fluid)))	USPAT; EPO; JPO; DERWEN	2003/06 /29 22:24			0
53	B RS	81	134/902.ccls. and (mov\$2 near2 nozzle)	USPAT; EPO; JPO; DERWEN	2003/06 /29 22:25			0
54	B RS	12	(134/902.ccls. and (mov\$2 near2 nozzle)) and (isoprop\$3 ipa) and (nitrogen inert)	USPAT; EPO; JPO; DERWEN	2003/06 /29 22:49			0
55	B RS	6	(134/902.ccls. and (mov\$2 near2 nozzle)) and (isoprop\$3 ipa) and bath	USPAT; EPO; JPO; DERWEN	2003/06 /29 22:51			0
56	B RS	1	((134/902.ccls. and (mov\$2 near2 nozzle)) and (isoprop\$3 ipa) and bath) not ((134/902.ccls. and (mov\$2 near2 nozzle)) and (isoprop\$3 ipa) and (nitrogen inert))	USPAT; EPO; JPO; DERWEN	2003/06 /29 22:50			0
57	B RS	14	(134/902.ccls. and (mov\$2 near2 nozzle)) and (isoprop\$3 ipa)	USPAT; EPO; JPO; DERWEN	2003/06 /29 22:51			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
58	B RS	8	((134/902.ccls. and (mov\$2 near2 nozzle)) and (isoprop\$3 ipa)) not ((134/902.ccls. and (mov\$2 near2 nozzle)) and (isoprop\$3 ipa) and bath) not (((134/902.ccls. and (mov\$2 near2 nozzle)) and (isoprop\$3 ipa) and bath) not ((134/902.ccls. and (mov\$2 near2 nozzle)) and (isoprop\$3 ipa) and (nitrogen inert)))	USPAT; EPO; JPO; DERWENT	2003/06 /29 23:02			0
59	B RS	11	("6478035" "6446643" "6247479" "5246023").pn.	USPAT; EPO; JPO; DERWENT	2003/06 /29 23:02			0
60	B RS	2	(("6478035" "6446643" "6247479" "5246023").pn.) and circulate	USPAT; EPO; JPO; DERWENT	2003/06 /29 23:03			0
61	B RS	6	(("6478035" "6446643" "6247479" "5246023").pn.) and circulat\$3	USPAT; EPO; JPO; DERWENT	2003/06 /29 23:32			0
62	B RS	14	("5951779" "5722442" "6247479" "6430840" "6412501" "6129100").pn.	USPAT; EPO; JPO; DERWENT	2003/06 /29 23:36			0
63	B RS	18	("5951779" "6412501" "6491045" "6123900" "6216709" "6247479" "6152153" "5954911").pn.	USPAT; EPO; JPO; DERWENT	2003/06 /29 23:37			0
64	B RS	8	("5951779" "6412501" "6491045" "6123900" "6216709" "6247479" "6152153" "5954911").pn.	USPAT; EPO; JPO	2003/06 /29 23:46			0
65	B RS	369	34/445,467,74.ccls. 134/11,30,31,95.1,902.ccls.	USPAT; EPO; JPO	2003/06 /29			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
66	B RS	133	(34/445,467,74.ccls. 134/11,30,31,95.1,902.ccls.) and isopropyl and inert and wafer	USPAT; EPO; JPO	2003/06 /29 23:47			0
67	B RS	13	((34/445,467,74.ccls. 134/11,30,31,95.1,902.ccls.) and isopropyl and inert and wafer) and (liquid near2 isopropyl)	USPAT; EPO; JPO	2003/06 /29 23:47			0

	Document ID	Issue Date	Title	Current OR	Current XRef	Inventor
1	US 6582525 B2	2003 0624	Methods for processing a workpiece using steam and ozone	134/2	134/19; 134/25. 4; 134/26; 134/28; 134/3; 134/30; 134/31; 134/33; 134/35; 134/36; 134/37; 134/41; 134/90 2	Bergman, Eric J.
2	US 6579382 B2	2003 0617	Chemical liquid processing apparatus for processing a substrate and the method thereof	134/3	134/21; 134/37; 134/90 2; 15/300. 1; 15/302; 15/303; 15/365; 427/24 0; 427/42 5; 438/74 5; 438/74 7; 438/74 8; 438/90 6	Ito, Shinichi
3	US 6578592 B1	2003 0617	Processing apparatus with horizontally movable enclosing element	134/2 00	118/50 1; 134/90	Kamikawa, Yuji et al.
4	US 6539959 B1	2003 0401	Cleaning apparatus for plate-like part and method thereof	134/1 53	134/1; 134/1.3 ;	Ohroku, Noriyuki et al.

	Document ID	Issue Date	Title	Current OR	Current XRef	Inventor
5	US 6539956 B1	2003 0401	Method and device for drying substrates	134/61	134/105; 134/90	Wolke, Klaus et al.
6	US 6536452 B1	2003 0325	Processing apparatus and processing method	134/117	134/148; 134/157; 134/183; 134/200; 134/90	Kohama, Kyouji et al.
7	US 6533872 B1	2003 0318	Method and arrangement for drying substrates after treatment in a liquid	134/30	134/26; 134/32; 134/902; 34/443; 34/444; 34/498	Leenaars, Adriaan F. M. et al.
8	US 6532975 B1	2003 0318	Substrate processing apparatus and substrate processing method	134/61	118/500; 134/140; 134/902; 414/589; 414/930	Kamikawa, Yuji et al.
9	US 6497768 B2	2002 1224	Process for treating a workpiece with hydrofluoric acid and ozone	134/3	134/2; 134/25.4; 134/30; 134/31; 134/33; 134/41; 134/902; 257/E2 1.228; 257/E2 1.229	Bergman, Eric J.

	Document ID	Issue Date	Title	Current OR	Current XRef	Inventor
10	US 6491043 B2	2002 12/10	Ultra-low particle semiconductor cleaner	134/2 5.4	134/2; 134/21; 134/26; 134/28; 134/3; 134/31; 134/34; 134/90 2; 257/E2 1.228	Mohindra, Raj et al.
11	US 6478035 B1	2002 11/12	Cleaning device, cleaning system, treating device and cleaning method	134/9 5.2	134/13 3; 134/18 2; 134/18 6; 134/90 2; 257/E2 1.577	Niuya, Takayuki et al.
12	US 6449873 B1	2002 09/17	Apparatus and method for dry cleaning of substrates using clusters	34/44 8	134/19 8; 134/37; 134/7; 134/90 2; 34/218; 34/232; 34/467; 34/487; 34/510; 34/516; 451/38; 451/39	Yoon, Deok-Joo et al.
13	US 6439247 B1	2002 08/27	Surface treatment of semiconductor substrates	134/1 02.1	134/90 2	Kittle, Paul A.

	Document ID	Issue Date	Title	Current OR	Current XRef	Inventor
14	US 6431190 B1	2002 0813	Fluid processing apparatus	134/148	134/13; 134/182; 134/90	Oka, Hitoshi et al.
15	US 6430840 B1	2002 0813	Method of and apparatus for drying a wafer using isopropyl alcohol	34/468	134/11; 134/30; 134/31; 134/902; 134/95.1; 257/E2 1.228; 34/408; 34/409; 34/410; 34/412; 34/443; 34/467; 34/74	Jung, Jae-Hyung
16	US 6412501 B1	2002 0702	Drying apparatus and drying method	134/95.2	134/102.1; 134/108; 134/902; 34/443; 34/469	Onoda, Hajime et al.
17	US 6412500 B1	2002 0702	Device and method for cleaning semiconductor wafers	134/64R	134/902; 15/77; 15/88.3; 257/E2	Brunner, Roland et al.
18	US 6394110 B2	2002 0528	Substrate processing apparatus and substrate processing method	134/61	134/902	Kamikawa, Yuji et al.

	Document ID	Issue Date	Title	Current OR	Current XRef	Inventor
19	US 6378534 B1	2002 0430	Semiconductor wafer cleaning system	134/1.3	134/18; 134/2; 134/25.4; 134/26; 134/90 2; 257/E2 1.228	Olesen, Michael B. et al.
20	US 6328809 B1	2001 1211	Vapor drying system and method	134/3	134/1; 134/2; 134/90	Elsawy, Tamer et al.
21	US 6315836 B1	2001 1113	Clean, recirculating processing method which prevents surface contamination of an object	134/10	134/15 3; 134/26, 134/3; 134/32, 134/33; 134/90 2; 216/92; 216/93	Oka, Hitoshi et al.
22	US 6312597 B1	2001 1106	Apparatus for delivering ultra-low particle counts in semiconductor manufacturing	210/243	134/90 2; 210/74 8; 210/90 0; 257/E2 1.228; 261/11 9.1; 261/4; 261/5	Mohindra, Raj et al.

	Document ID	Issue Date	Title	Current OR	Current XRef	Inventor
23	US 6299696 B1	2001 10/09	Substrate processing apparatus and substrate processing method	134/2	134/19; 134/26; 134/28; 134/29; 134/3; 134/30; 134/31; 134/32; 134/34; 134/35; 134/36; 134/41; 134/61; 134/90 2; 134/95. 2; 134/95. 3	Kamikawa, Yuji et al.
24	US 6247479 B1	2001 06/19	Washing/drying process apparatus and washing/drying process method	134/9 5.2	134/13 3; 134/15 3; 134/90 2; 134/95. 3	Taniyama, Hiroki et al.
25	US 6230721 B1	2001 05/15	Processing apparatus and method, robot apparatus	134/6 1	134/13 3; 134/66; 134/90	Miyasako, Hisaoaki
26	US 6221171 B1	2001 04/24	Method and apparatus for conveying a workpiece	134/3 2	134/33; 134/90 2	Maekawa, Toshiro et al.

	Document ID	Issue Date	Title	Current OR	Current XRef	Inventor
27	US 6216709 B1	2001 0417	Method for drying a substrate	134/2 5.4	134/2; 134/26; 134/30; 134/32; 134/37; 134/90 2; 134/95. 2	Fung, Robert Pui Chi et al.
28	US 6170495 B1	2001 0109	Apparatus for treating substrates using the marangoni effect	134/6 1	134/10 2.3; 134/90 2; 134/95. 2	Leenaars, Adriaan F. M. et al.
29	US 6168660 B1	2001 0102	Spin coating bowl	118/5 2	118/31 9; 118/32 0; 118/56; 134/15 3; 134/90 2; 427/24 2	Hayes, Bruce L. et al.
30	US 6158446 A	2000 1212	Ultra-low particle semiconductor cleaner	134/2 5.4	134/2; 134/21; 134/25. 5; 134/26; 134/30; 134/37; 134/90 2; 257/E2 1.228	Mohindra, Raj et al.

	Document ID	Issue Date	Title	Current OR	Current XRef	Inventor
31	US 6158445 A	2000 1212	Semiconductor wafer cleaning method	134/1.3	134/2; 134/26; 134/28; 134/3; 134/34; 134/41; 134/90 2; 257/E2 1.228	Olesen, Michael B. et al.
32	US 6139645 A	2000 1031	Method and arrangement for drying substrates after treatment in a liquid	134/3.0	134/26; 134/32; 134/90 2; 34/443; 34/444; 34/498	Leenaars, Adriaan F. M. et al.
33	US 6129100 A	2000 1010	Wafer cleaning apparatus and structure for holding and transferring wafer used in wafer cleaning apparatus	134/6.1	134/10 0.1; 134/11 3; 134/15 7; 134/90 2; 134/94. 1	Kitagawa, Kenichi et al.
34	US 6062240 A	2000 0516	Treatment device	134/9.5.2	134/15 3; 134/90 2; 134/95. 3	Sada, Tetsuya et al.

	Document ID	Issue Date	Title	Current OR	Current XRef	Inventor
35	US 6045621 A	2000 0404	Method for cleaning objects using a fluid charge	134/2	134/10; 134/11; 134/25. 4; 134/25. 5; 134/26; 134/30; 134/34; 134/36; 134/90 2; 134/95. 1; 134/95. 2	Puri, Suraj et al.
36	US 6001191 A	1999 1214	Substrate washing method, substrate washing-drying method, substrate washing apparatus and substrate washing-drying apparatus	134/32	134/2; 134/34; 134/61; 134/90 2; 257/E2 1.228	Kamikawa, Yuuji et al.
37	US 5988189 A	1999 1123	Method and apparatus for cleaning wafers using multiple tanks	134/95.2	134/10 2.3; 134/10 8; 134/18 4; 134/18 6; 134/20 1; 134/90 2; 257/E2 1.228	Mohindra, Raj et al.

	Document ID	Issue Date	Title	Current OR	Current XRef	Inventor
38	US 5958146 A	1999 0928	Ultra-low particle semiconductor cleaner using heated fluids	134/2	134/19; 134/21; 134/25. 4; 134/25. 5; 134/26; 134/30; 134/37; 134/90 2; 34/78	Mohindra, Raj et al.
39	US 5951779 A	1999 0914	Treatment method of semiconductor wafers and the like and treatment system for the same	134/2	134/21; 134/30; 134/31; 134/32; 134/90 2; 134/95. 2; 257/E2 1.228	Koyanagi, Tetsuo et al.
40	US 5950645 A	1999 0914	Semiconductor wafer cleaning system	134/9 8.1	134/10 0.1; 134/11 3; 134/18 4; 134/18 6; 134/90 2; 257/E2 1.228	Olesen, Michael B. et al.

	Document ID	Issue Date	Title	Current OR	Current XRef	Inventor
41	US 5932027 A	1999 0803	Cleaning and drying photoresist coated wafers	134/21	134/2; 134/25.4; 134/25.5; 134/26; 134/30; 134/37; 134/902; 257/E2 1.228	Mohindra, Raj et al.
42	US 5927303 A	1999 0727	Substrate processing apparatus	134/148	134/153; 134/200; 134/90	Miya, Katsuhiko et al.